# BLP9G0722-20; BLP9G0722-20G Power LDMOS transistor Rev. 3 – 26 February 2018

AMPLEON Product data sheet

#### **Product profile** 1.

### 1.1 General description

20 W plastic LDMOS power transistor for base station applications at frequencies from 100 MHz to 2700 MHz.

#### **Application performance (multiple frequencies)** Table 1.

Typical RF performance at T<sub>case</sub> = 25 ℃; I<sub>Da</sub> = 180 mA; in a class-AB demo board, tested on gull wing lead device.

Test signal	f	I <sub>Dq</sub>	V <sub>DS</sub>	P <sub>L(AV)</sub>	Gp	ησ	ACPR <sub>5M</sub>
	(MHz)	(mA)	(V)	(dBm)	(dB)	(%)	(dBc)
1-carrier W-CDMA	400 to 430	180	28	35	25.5	24	-45 <mark>[1]</mark>
	728 to 768	180	28	35	23	22	-45 <mark>[1]</mark>
	1805 to 1880	180	28	35	19	21	-45 <mark>[1]</mark>
	2110 to 2170	180	28	35	18	21	-45 <mark>[1]</mark>
	2300 to 2400	180	28	35	17.3	21	-45 <mark>[1]</mark>
	2570 to 2620	180	28	35	16	20	-45 <mark>[1]</mark>

[1] Test signal: 3GPP test model 1; 64 DCHP; PAR = 7.2 dB at 0.01 % probability on CCDF.

### 1.2 Features and benefits

- High efficiency
- Excellent ruggedness
- Designed for broadband operation
- Excellent thermal stability
- High power gain
- Integrated ESD protection
- Compliant to Directive 2002/95/EC, regarding Restriction of Hazardous Substances (RoHS)

### 1.3 Applications

- FDD/TDD LTE
- GSM EDGE
- CDMA

- W-CDMA MC-GSM
- WiMAX

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### 2. Pinning information

Pin	Description	Simplified outline	Graphic symbol
BLP9G07	22-20 (SOT1482-1)		
1	drain	Ž	
2	gate	الم	1 لــــا
3	source		2 – – – – – – – – – – – – – – – – – – –
BLP9G07	22-20G (SOT1483-1)		
1	drain	2	
2	gate		
3	source		2

[1] Connected to flange.

### 3. Ordering information

### Table 3.Ordering information

Type number	Package					
	Name	Description	Version			
BLP9G0722-20	-	plastic; heatsink small outline package; 2 leads (flat)	SOT1482-1			
BLP9G0722-20G	-	plastic; heatsink small outline package; 2 leads	SOT1483-1			

### 4. Limiting values

#### Table 4.Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>DS</sub>	drain-source voltage		-	65	V
V <sub>GS</sub>	gate-source voltage		-5	+13	V
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		-	225	°C

### 5. Thermal characteristics

### Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Тур	Unit
R <sub>th(j-c)</sub>	thermal resistance from junction to case	$T_{case}$ = 80 °C; $P_L$ = 3 W	1.1	K/W

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### 6. Characteristics

#### Table 6.DC characteristics

 $T_i = 25 \ ^{\circ}C$ ; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V <sub>(BR)DSS</sub>	drain-source breakdown voltage	V <sub>GS</sub> = 0 V; I <sub>D</sub> = 0.3 mA	65	-	-	V
V <sub>GS(th)</sub>	gate-source threshold voltage	V <sub>DS</sub> = 10 V; I <sub>D</sub> = 30 mA	1.5	2.0	-	V
V <sub>GSq</sub>	gate-source quiescent voltage	V <sub>DS</sub> = 28 V; I <sub>D</sub> = 180 mA	1.6	2.1	2.6	V
I <sub>DSS</sub>	drain leakage current	V <sub>GS</sub> = 0 V; V <sub>DS</sub> = 28 V	-	-	1.4	μA
I <sub>DSX</sub>	drain cut-off current	$V_{GS} = V_{GS(th)} + 3.75 V$	-	6	-	А
I <sub>GSS</sub>	gate leakage current	V <sub>GS</sub> = 11 V; V <sub>DS</sub> = 0 V	-	-	140	nA
9 <sub>fs</sub>	forward transconductance	V <sub>DS</sub> = 10 V; I <sub>D</sub> = 30 mA	-	300	-	mS
R <sub>DS(on)</sub>	drain-source on-state resistance	$V_{GS} = V_{GS(th)} + 3.75 V;$ I <sub>D</sub> = 1.05 A	-	500	-	mΩ

### Table 7. RF characteristics

A derivative functional RF test is performed in production. The performance as mentioned below is verified by design and characterization in a class AB production board.

Test signal: pulsed CW;  $\delta$  = 10%;  $t_p$  = 100  $\mu$ s;  $V_{DS}$  = 28 V;  $I_{Dq}$  = 180 mA;  $T_{case}$  = 25 °C; f = 1842.5 MHz.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
G <sub>p</sub>	power gain	P <sub>L(AV)</sub> = 35 dBm	17	19	-	dB
$\eta_D$	drain efficiency	P <sub>L(AV)</sub> = 35 dBm	18	22	-	%
RL <sub>in</sub>	input return loss	P <sub>L(AV)</sub> = 35 dBm	-	-10	-6	dB
P <sub>L(1dB)</sub>	output power at 1 dB gain compression		42.5	43.9	-	dBm
P <sub>L(3dB)</sub>	output power at 3 dB gain compression		43	44.3	-	dBm

### 7. Test information

### 7.1 Ruggedness in Doherty operation

The BLP9G0722-20 and BLP9G0722-20G are capable of withstanding a load mismatch corresponding to a VSWR = 10 : 1 through all phases under the following conditions:  $V_{DS}$  = 28 V;  $P_{L}$  = 20 W (CW); f = 728 MHz and 1805 MHz on development board.

### 7.2 Impedance information

Table 8.Typical impedance of BLP9G0722-20GMeasured load-pull data;  $I_{Da}$  = 180 mA;  $V_{DS}$  = 28 V.

f	Z <sub>S</sub> [1]	Z <sub>L</sub> [1]	PL <sup>[2]</sup>	η <mark>ρ <mark>[2]</mark></mark>	G <sub>p</sub> [2]		
(MHz)	(Ω)	<b>(</b> Ω <b>)</b>	(W)	(%)	(dB)		
Maximum	Maximum power load						
740	0.5 + j0.1	10.6 – j1.0	37	55.1	22.8		
880	0.6 – j1.4	3.8 + j2.0	49	70.9	22.8		
1810	1.6 – j5.5	3.4 – j1.0	43	62.2	19.0		

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f	Z <sub>S</sub> [1]	Z <sub>L</sub> [1]	PL [2]	ח <mark>ם [2]</mark>	G <sub>p</sub> [2]
(MHz)	(Ω)	(Ω)	(W)	(%)	(dB)
1840	1.3 – j5.8	3.0 – j1.2	43	62.7	19.1
1880	1.3 – j6.2	2.6 – j1.5	42	61.2	18.7
2110	5.3 – j9.6	2.6 – j2.5	41	58.2	17.7
2170	6.2 – j8.1	2.6 – j2.5	41	60.4	18.2
Maximum	drain efficiency lo	ad			
740	0.5 + j0.1	6.0 + j10.0	20	74.1	24.8
880	0.6 - j1.4	3.7 + j5.9	26	82.7	24.7
1810	1.6 – j5.5	1.9 + j0.2	31	70.9	20.9
1840	1.3 – j5.8	1.7 + j0.0	29	69.8	21.3
1880	1.3 – j6.2	1.6 – j0.2	28	69.8	21.3
2110	5.3 – j9.6	1.7 – j1.5	32	65.6	19.5
2170	6.2 – j8.1	1.6 – j1.7	30	65.9	20.2

# Table 8.Typical impedance of BLP9G0722-20G...continuedMeasured load-pull data: $I_{Da}$ = 180 mA: $V_{DS}$ = 28 V.

[1]  $Z_S$  and  $Z_L$  defined in Figure 1.

[2] at 3 dB gain compression.

#### Table 9. Typical impedance of BLP9G0722-20

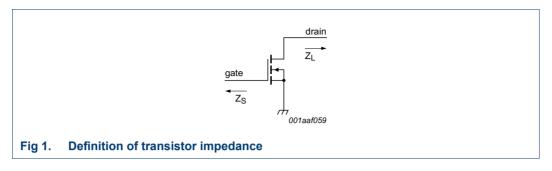
Measured load-pull data;  $I_{Dq}$  = 180 mA;  $V_{DS}$  = 28 V.

f	Z <sub>S</sub> [1]	Z <sub>L</sub> [1]	P <sub>L</sub> [2]	η <mark>ρ [2]</mark>	G <sub>p</sub> [2]
(MHz)	(Ω)	(Ω)	(W)	(%)	(dB)
Maximum	power load				
740	0.6 + j0.6	10.6 – j1.0	39	56.8	22.7
880	0.6 – j0.7	4.0 + j1.6	51	70.9	22.1
1810	1.8 – j5.4	3.0 - j1.2	44	60.9	19.1
1840	1.6 – j5.8	3.0 - j1.2	44	62.6	19.6
1880	1.8 – j6.1	2.9 – j1.6	44	60.9	19.1
2110	7.3 – j8.2	2.6 – j2.5	41	57.7	17.8
2170	8.7 – j6.8	2.6 – j2.5	43	62.1	18.7
Maximum	drain efficiency lo	ad			
740	0.6 + j0.6	6.0 + j10.0	22	77.0	24.6
880	0.6 – j0.7	3.7 + j5.9	26	85.3	24.4
1810	1.8 – j5.4	1.9 + j0.0	33	69.4	20.9
1840	1.6 – j5.8	1.9 + j0.0	31	69.4	21.7
1880	1.8 – j6.1	1.8 – j0.2	32	70.7	21.6
2110	7.3 – j8.2	1.5 – j1.4	30	65.3	19.9
2170	8.7 – j6.8	1.4 – j1.6	29	69.3	21.3

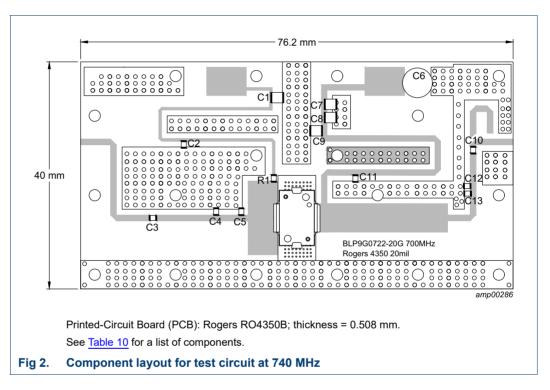
[1]  $Z_S$  and  $Z_L$  defined in Figure 1.

[2] at 3 dB gain compression.

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### 7.3 Test circuit



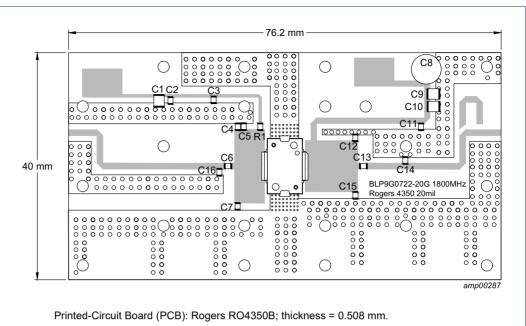
#### Table 10. List of components

See Figure 2 for component layout.

Component	Description	Value	Remarks
C1, C7, C8, C9	multilayer ceramic chip capacitor	10 μF, 50 V	Murata
C2, C3, C10, C11	multilayer ceramic chip capacitor	36 pF	ATC 600F
C4, C5	multilayer ceramic chip capacitor	15 pF	ATC 600F
C6	electrolytic capacitor	2200 μF, 50 V	
C12	multilayer ceramic chip capacitor	5.6 pF	ATC 600F
C13	multilayer ceramic chip capacitor	0.2 pF	ATC 600F
R1	resistor	5.1 Ω	SMD 0805

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See Table 11 for a list of components.

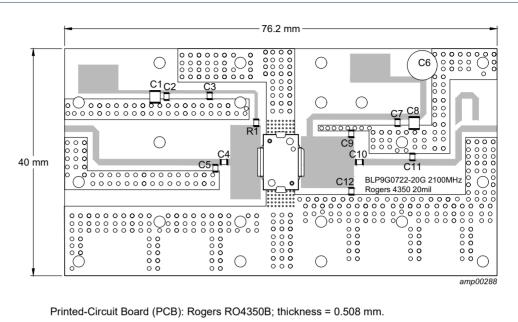
#### Fig 3. Component layout for test circuit at 1800 MHz

### Table 11.List of components

See Figure 3 for component layout.

Component	Description	Value	Remarks
C1, C9, C10	multilayer ceramic chip capacitor	10 μF, 50 V	Murata
C2, C3, C11, C13	multilayer ceramic chip capacitor	12 pF	ATC 600F
C4, C5	multilayer ceramic chip capacitor	0.8 pF	ATC 600F
C6	multilayer ceramic chip capacitor	6.2 pF	ATC 600F
C7	multilayer ceramic chip capacitor	2 pF	ATC 600F
C8	electrolytic capacitor	2200 μF, 50 V	
C12, C15	multilayer ceramic chip capacitor	0.3 pF	ATC 600F
C14	multilayer ceramic chip capacitor	2.2 pF	ATC 600F
C16	multilayer ceramic chip capacitor	0.3 pF	ATC 600F
R1	resistor	5.1 Ω	SMD 0805

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See Table 12 for a list of components.

#### Fig 4. Component layout for test circuit at 2100 MHz

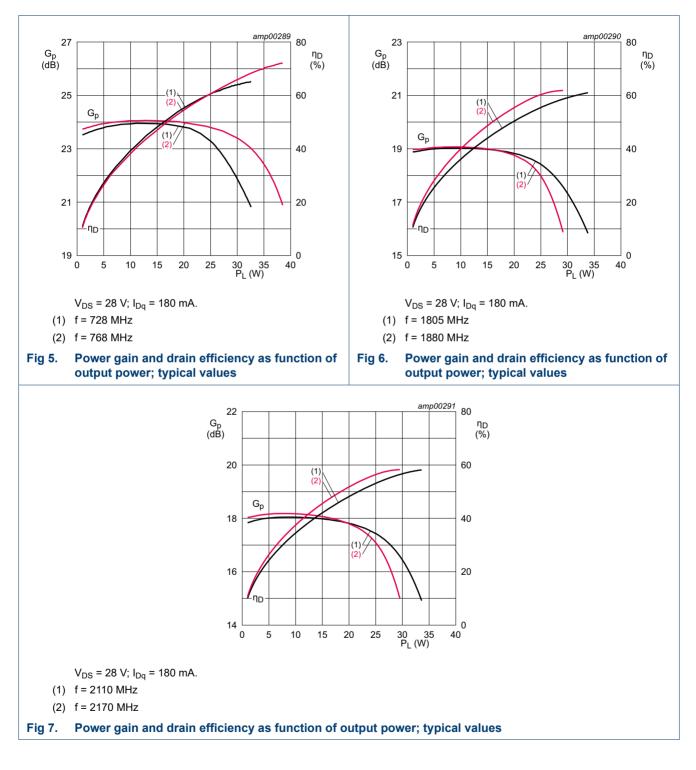
# Table 12.List of componentsSee Figure 4 for component layout.

Component	Description	Value	Remarks
C1, C8	multilayer ceramic chip capacitor	10 μF, 50 V	Murata
C2, C7, C10	multilayer ceramic chip capacitor	12 pF	ATC 600F
C3	multilayer ceramic chip capacitor	62 pF	ATC 600F
C4	multilayer ceramic chip capacitor	5.6 pF	ATC 600F
C5	multilayer ceramic chip capacitor	0.5 pF	ATC 600F
C6	electrolytic capacitor	2200 μF, 50 V	
C9	multilayer ceramic chip capacitor	2.2 pF	ATC 600F
C11	multilayer ceramic chip capacitor	1.2 pF	ATC 600F
C12	multilayer ceramic chip capacitor	1.8 pF	ATC 600F
R1	resistor	5.1 Ω	SMD 0805

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7.4 Graphical data

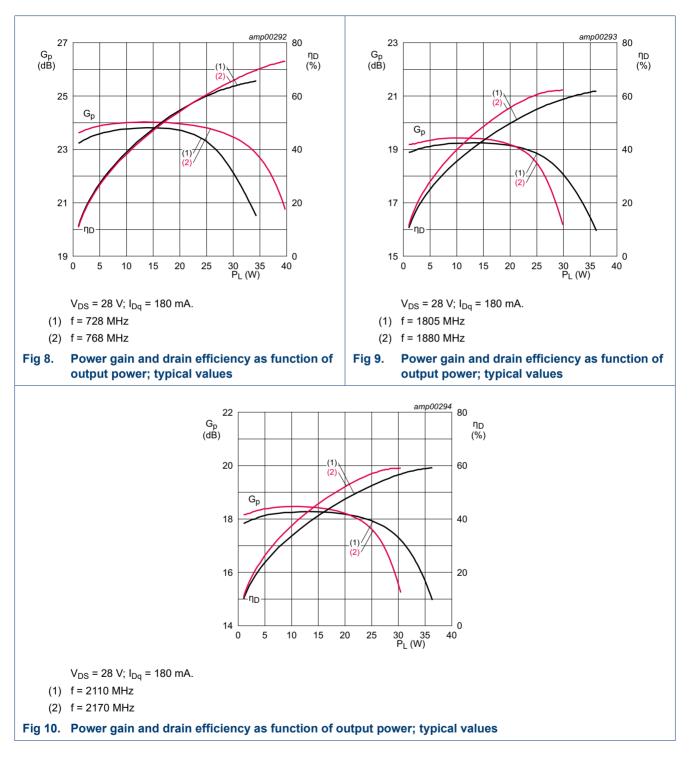
7.4.1 CW



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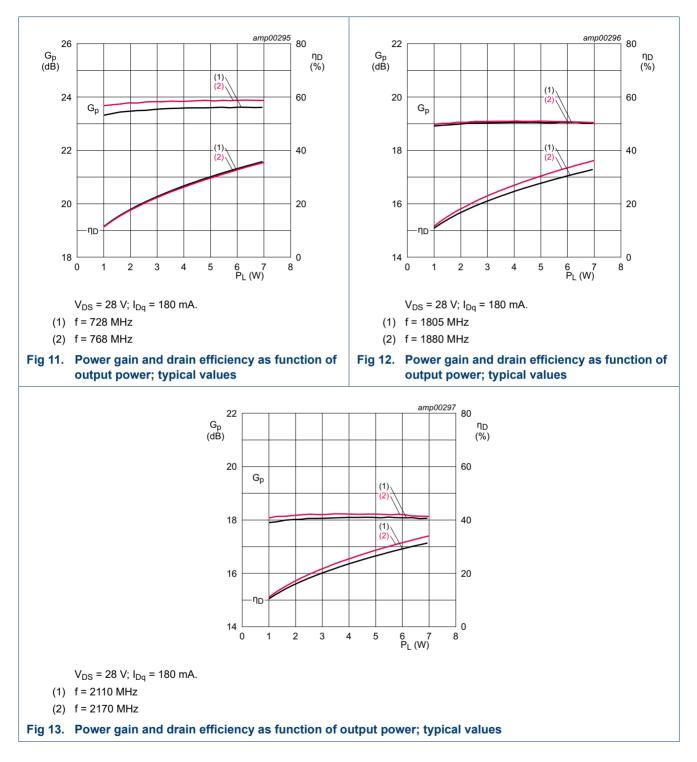
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### 7.4.2 Pulsed CW

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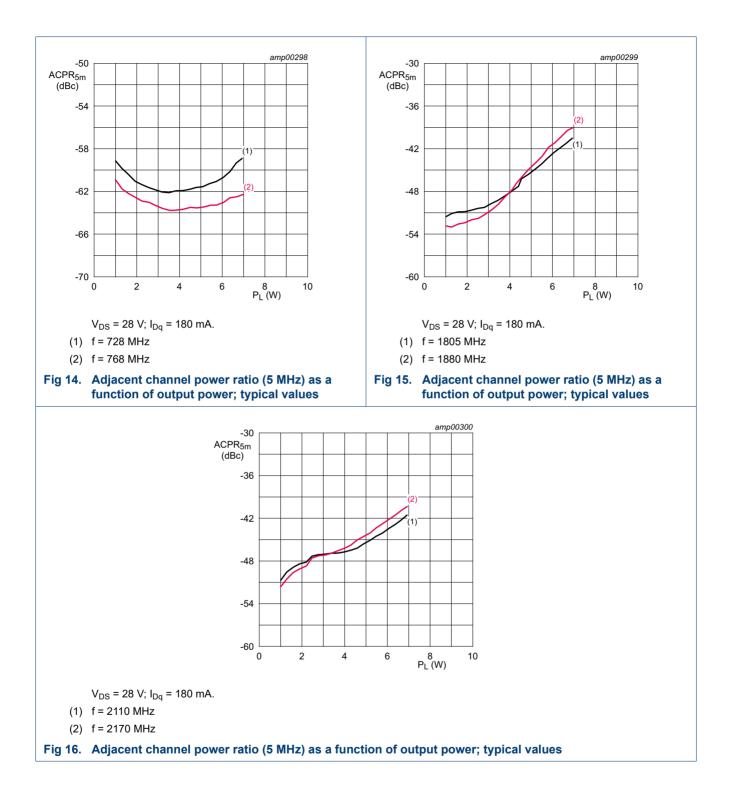


### 7.4.3 1-Carrier W-CDMA

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### 8. Package outline

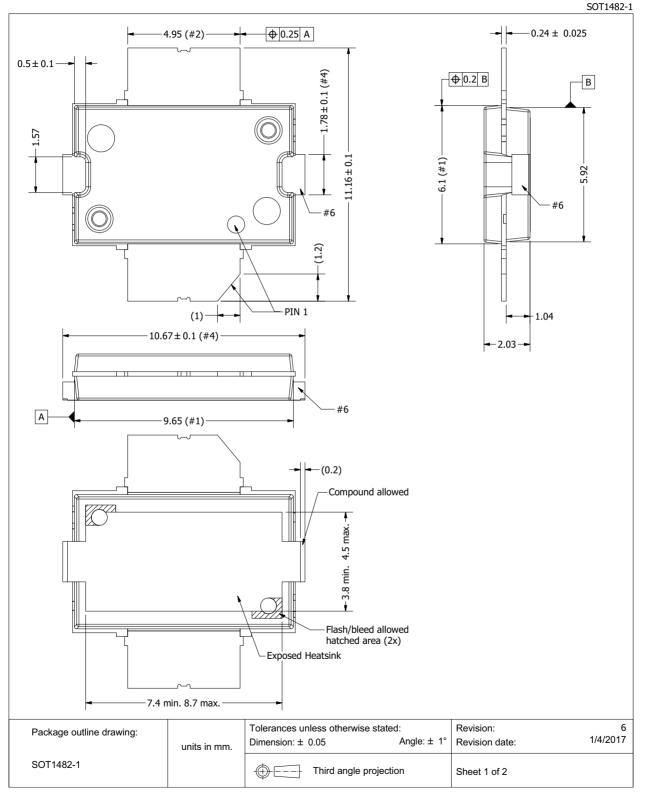


Fig 17. Package outline SOT1482-1 (sheet 1 of 2)

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SOT1482-1

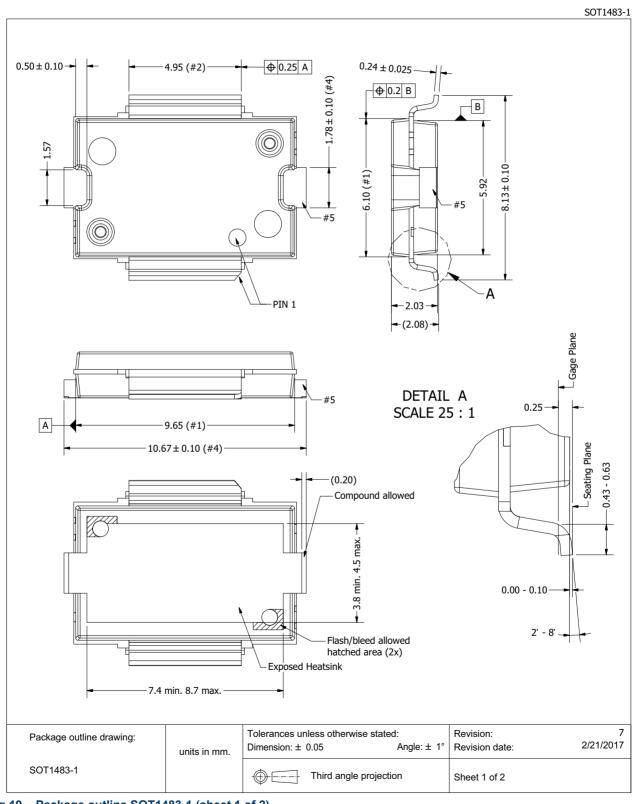
				rawing Notes			
Items				Descriptio			
(1)	Dimensions are exc	luding mold protru	usion. The m	old protrusion is	maximum 0.15 mm	per side. See also de	ətail B.
( )	In the dambar area	max. protrusion is	s 0.55 mm. m	ax. in length an	d 0.3 mm. max. in wi	dth (4x). See also de	etail B.
(2)	The lead dambar (n	netal) protrusions	are not inclue	ded. Add 0.14 m	m max to the total le	ead dimension at the	dambar location.
(3)	The leads and expo	sed heatsink are	plated with m	atte Tin (Sn).			
(4)	Dimensions (Heatsi	Dimensions (Heatsink ears) 10,67 and 1,78 do not include mouldprotrusion. Overall Max. dimensions incl. mould					
( )	protrusions is 10.92	mm. (max.) and 2	2.03 mm. (ma	ax.)			
(5)	Lead coplanarity ov	er the leads is 0,1	mm. maxim	um.			
(6)	Surfaces may rema	in unplated (not s	olderable sur	faces)			
			7	(0.3 ma	~ }		TAIL B LE 50 : 1
	B-∕	Lead Dar	(9.55 may) mbar prote			0.15 max	x. (#1)
ackage of	B →	Lead Dar	mbar proti	rusion (#2)		Revision:	x. (#1)-

### Fig 18. Package outline SOT1482-1 (sheet 2 of 2)

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### Fig 19. Package outline SOT1483-1 (sheet 1 of 2)

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SOT1483-1

			Drawing Notes			
Items			Description			
(1)	Dimensions are excluding mold protrusion. The mold protrusion is maximum 0.15 mm per side. See also detail B.					
	In the dambar area	max. protrusion is	is 0.55mm max. in lenght and 0.3 mm max. in width (4x) See also detail B	l		
(2)	The lead dambar (metal) protrusions are not included. Add 0.14 mm max to the total lead dimension at the dambar location.					
(3)	The leads and exposed heatsink are plated with matte Tin (Sn).					
(4)	Dimensions (Heatsink ears) 10,67 and 1,78 do not include mouldprotrusion. Overall Max. dimensions incl. mould					
. /	protrusions is 10,92	mm. (max.) and 2	2,03 mm. (max.).			
(5)	Surfaces may rema	in unplated (not so	solderable surfaces).			
			χ.			
B-			DETAIL B SCALE 50 : 1			
	utline drawing:			2/21/2		

#### Fig 20. Package outline SOT1483-1 (sheet 2 of 2)

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### 9. Handling information

#### CAUTION



This device is sensitive to ElectroStatic Discharge (ESD). Observe precautions for handling electrostatic sensitive devices.

Such precautions are described in the ANSI/ESD S20.20, IEC/ST 61340-5, JESD625-A or equivalent standards.

#### Table 13.ESD sensitivity

ESD model	Class
Charged Device Model (CDM); According to ANSI/ESDA/JEDEC standard JS-002	C2A [1]
Human Body Model (HBM); According to ANSI/ESDA/JEDEC standard JS-001	2 [2]

 CDM classification C2A is granted to any part that passes after exposure to an ESD pulse of 500 V, but fails after exposure to an ESD pulse of 750 V.

[2] HBM classification 2 is granted to any part that passes after exposure to an ESD pulse of 2000 V, but fails after exposure to an ESD pulse of 4000 V.

### **10. Abbreviations**

Table 14. Abbreviations				
Acronym	Description			
3GPP	3rd Generation Partnership Project			
CCDF	Complementary Cumulative Distribution Function			
CDMA	Code Division Multiple Access			
CW	Continuous Wave			
DCPH	Dedicated Physical CHannel			
EDGE	Enhanced Data rates for GSM Evolution			
ESD	ElectroStatic Discharge			
FDD	Frequency Division Duplex			
GSM	Global System for Mobile Communication			
LDMOS	Laterally Diffused Metal-Oxide Semiconductor			
LTE	Long Term Evolution			
MC-GSM	Multi Carrier GSM			
MTF	Median Time to Failure			
PAR	Peak-to-Average Ratio			
SMD	Surface Mounted Device			
TDD	Time Division Duplex			
W-CDMA	Wideband Code Division Multiple Access			
WiMAX	Worldwide Interoperability for Microwave Access			

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# 11. Revision history

### Table 15. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes	
BLP9G0722-20_9G0722-20G v.3	20180226	Product data sheet	-	BLP9G0722-20_9G0722-20G v.2	
Modifications:	<u>Section 1.1 on page 1</u> : changed "400 MHz" to "100 MHz"				
BLP9G0722-20_9G0722-20G v.2	20170801	Product data sheet	-	BLP9G0722-20_9G0722-20G v.1	
BLP9G0722-20_9G0722-20G v.1	20170606	Product data sheet	-	-	

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# 12. Legal information

### 12.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.ampleon.com.

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